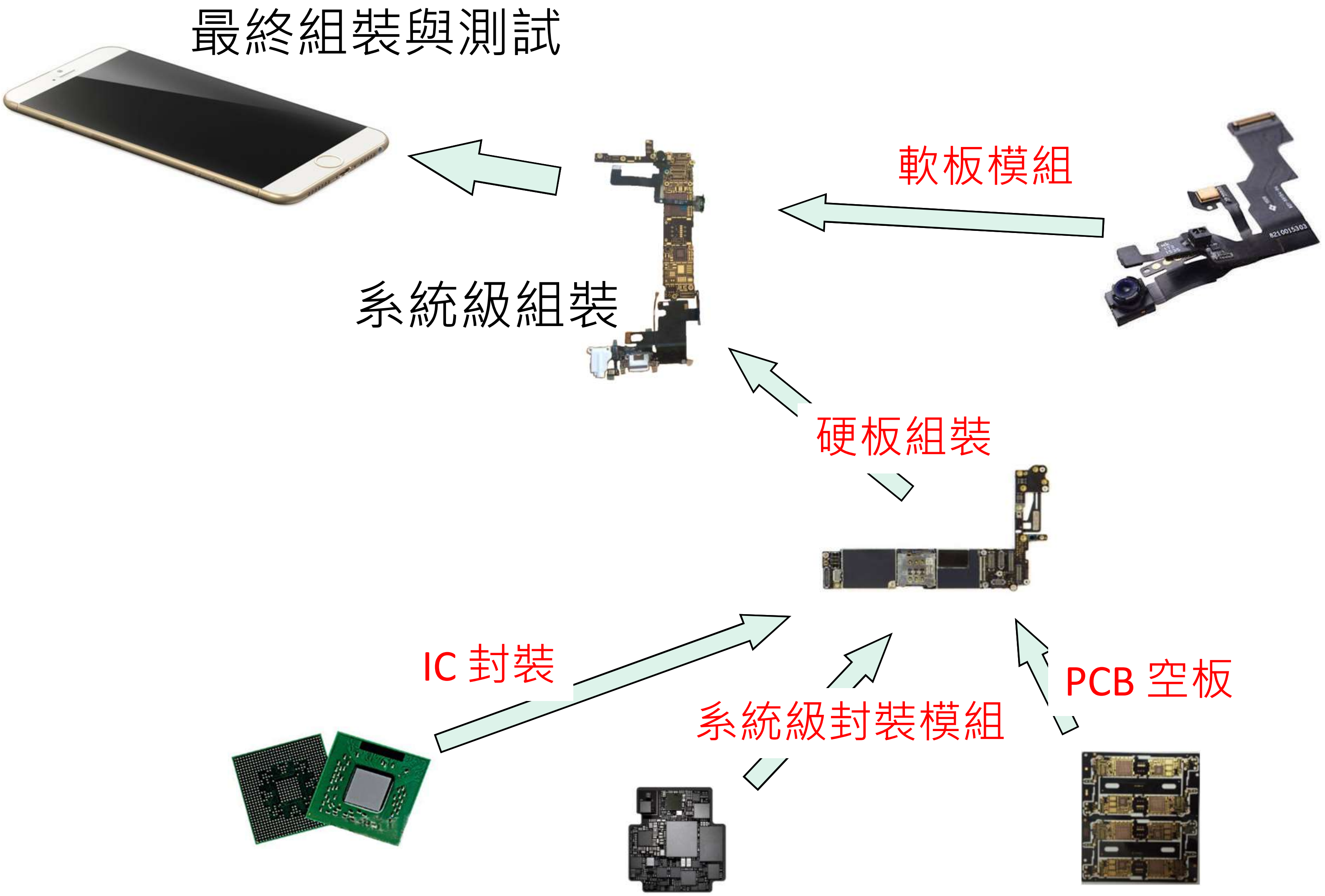
景碩科技股份有限公司

Kinsus Interconnect Technology Corp.

Feb 2026

IC 封裝技術
IC Packaging Technology

電子產品構裝的各個層次



最終組裝與測試

軟板模組

系統級組裝

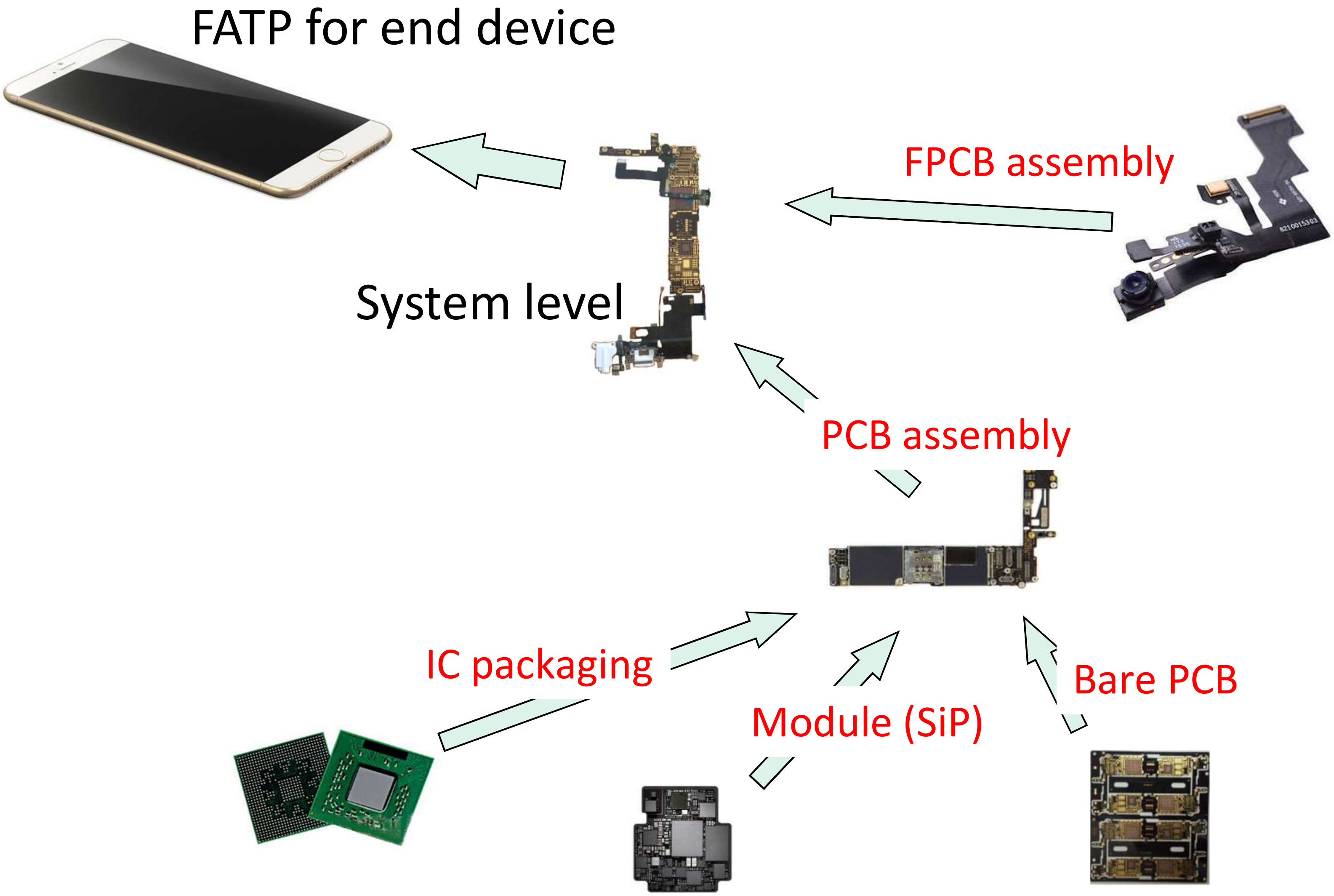
硬板組裝

IC 封裝

PCB 空板

系統級封裝模組

Levels of Assembly



FATP for end device

System level

FPCB assembly

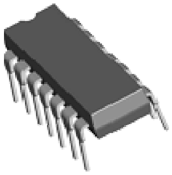
PCB assembly

IC packaging

Module (SiP)

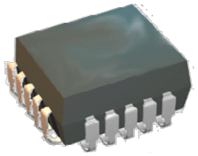
Bare PCB

各種形式的IC 封裝

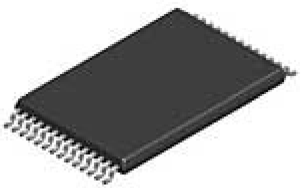


DIP

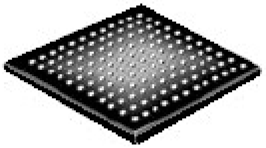
QFP



PLCC

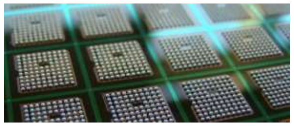


TSOP

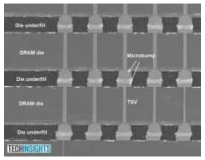


PBGA/
Flip-Chip BGA

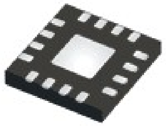
CSP



WLP

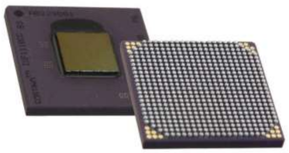


TSV

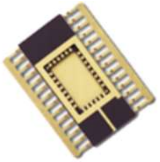


QFN

DFN



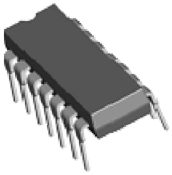
Ceramic BGA



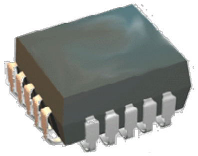
Ceramic chip

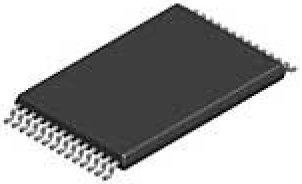
BGA 封裝 市場規模: 2023 年828 億顆, 產值 161億美元

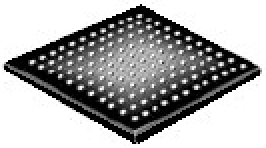
Different types of IC packaging


DIP

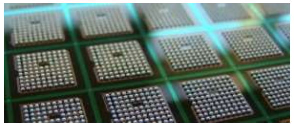

QFP

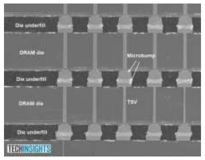

PLCC


TSOP

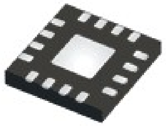

PBGA/
Flip-Chip BGA


CSP

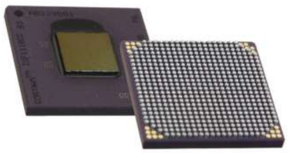

WLP

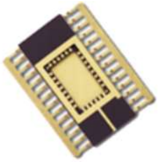


TSV


QFN

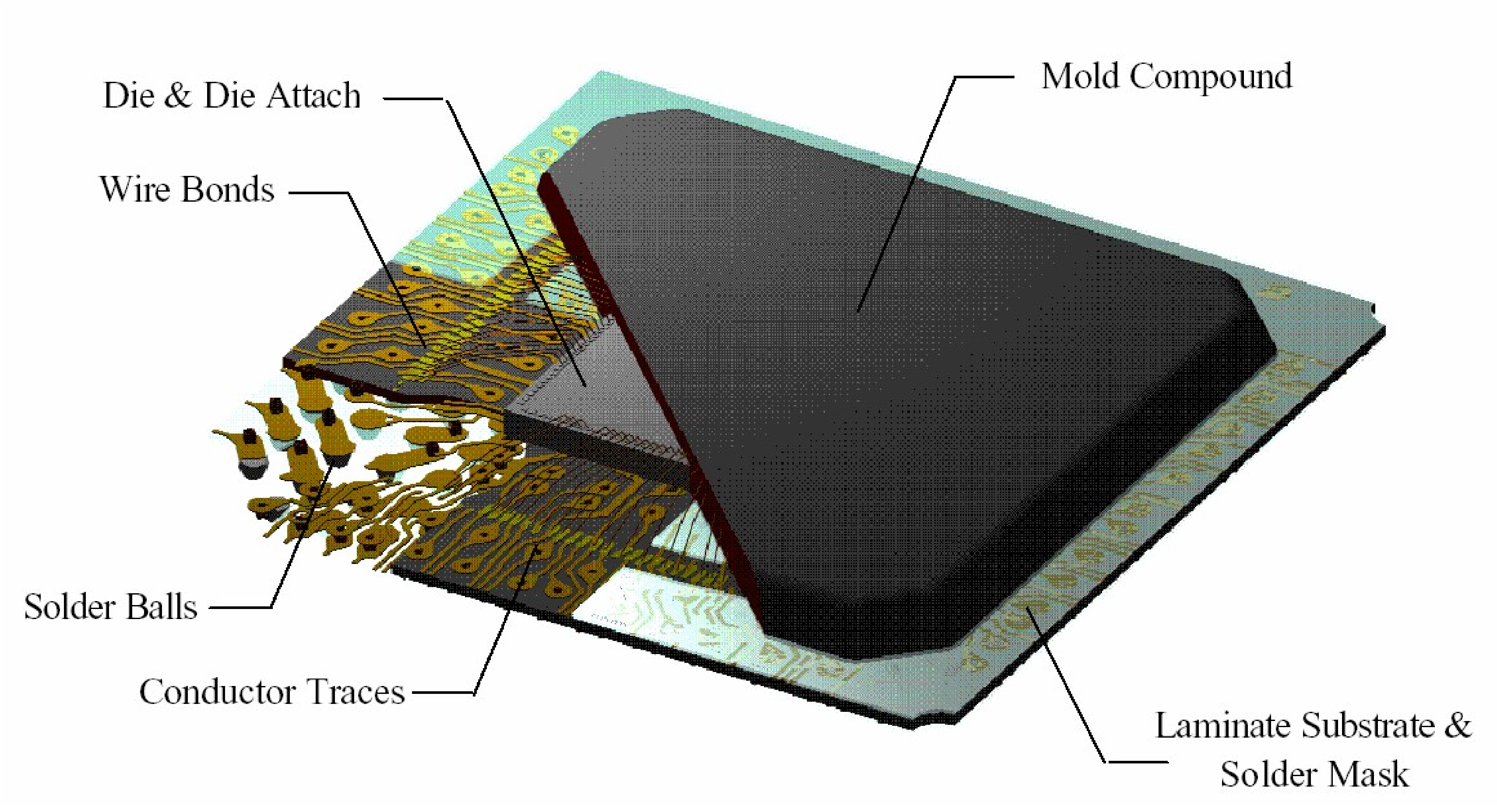

DFN


Ceramic BGA

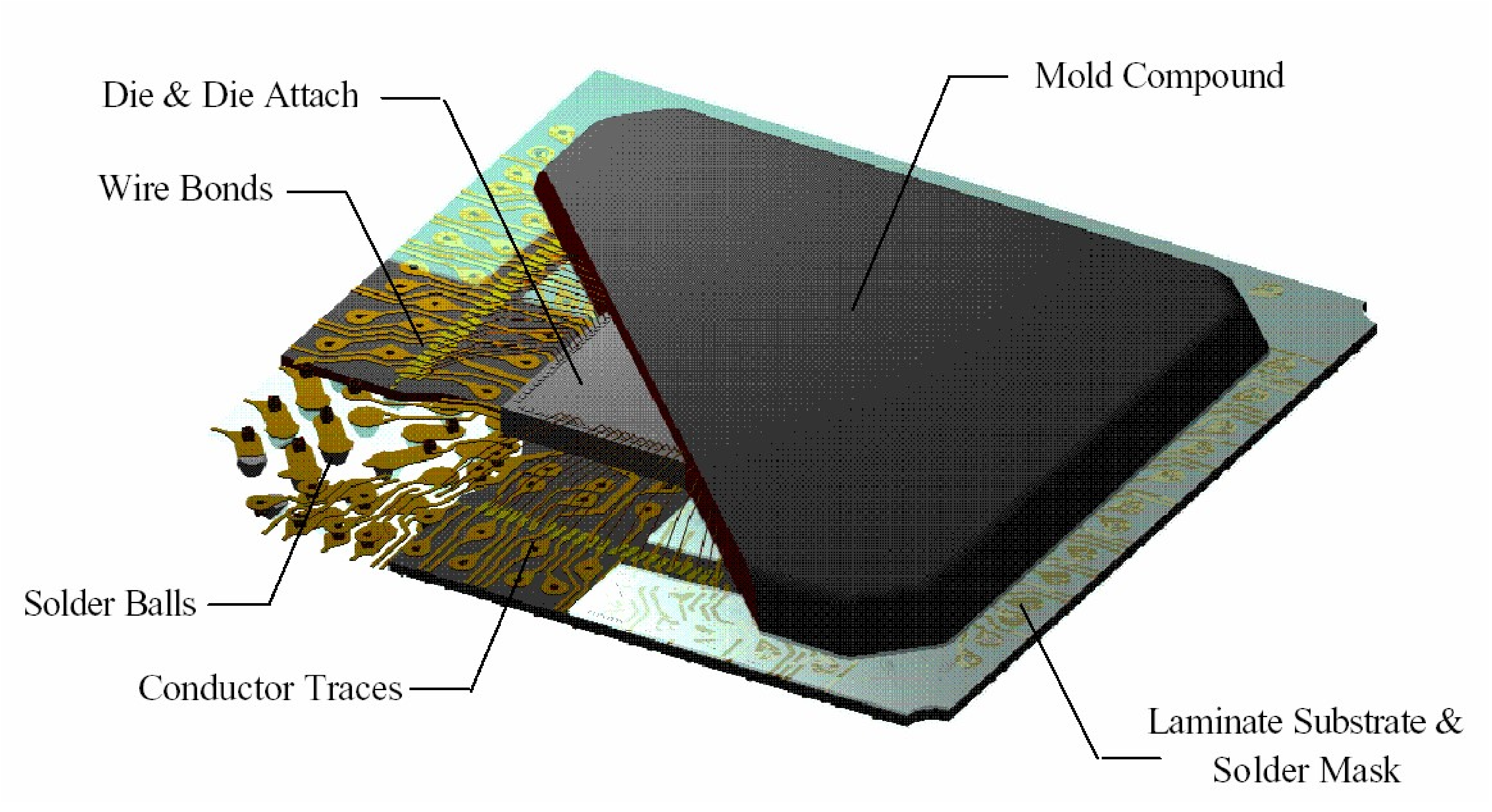

Ceramic chip

BGA Market size : 82 Billion units, 16 Billion US$ in 2023

IC 結構

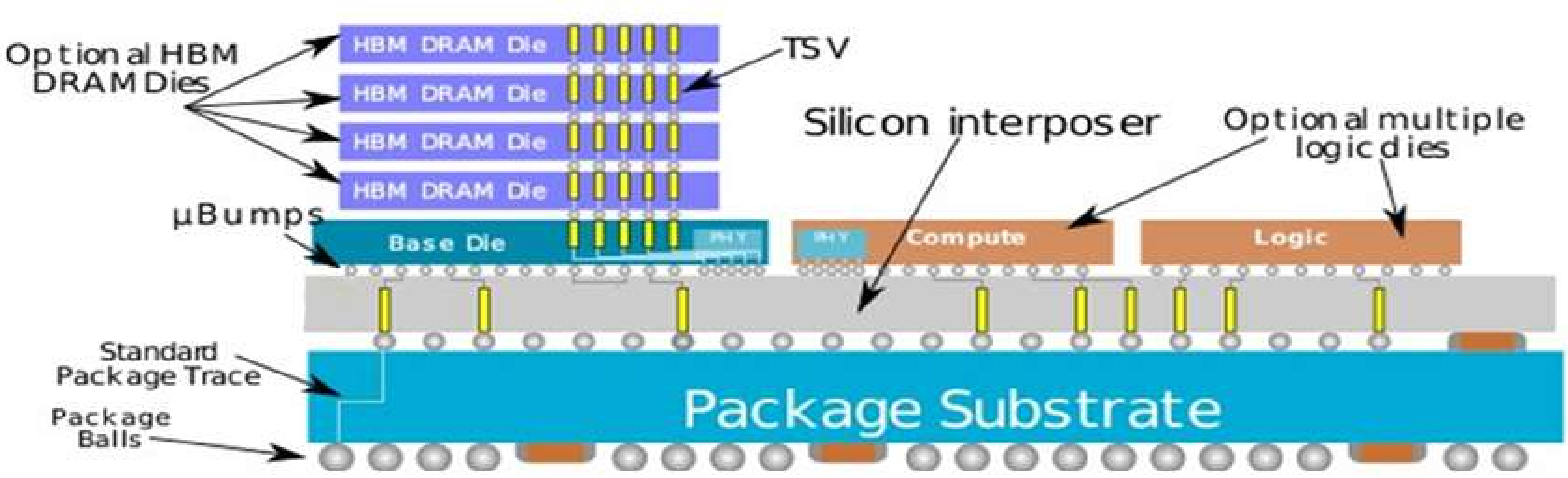

Die & Die Attach
Wire Bonds
Mold Compound
Solder Balls
Conductor Traces
Laminate Substrate &
Solder Mask

What Substrate Makers do?



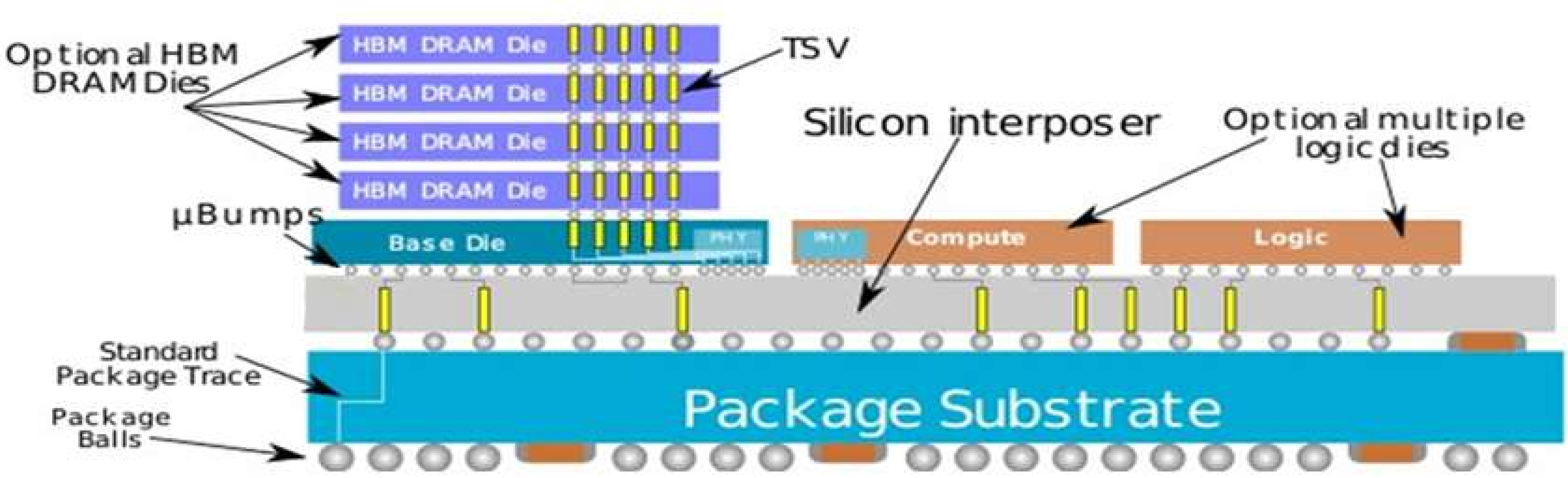
先進封裝結構

CoWoS

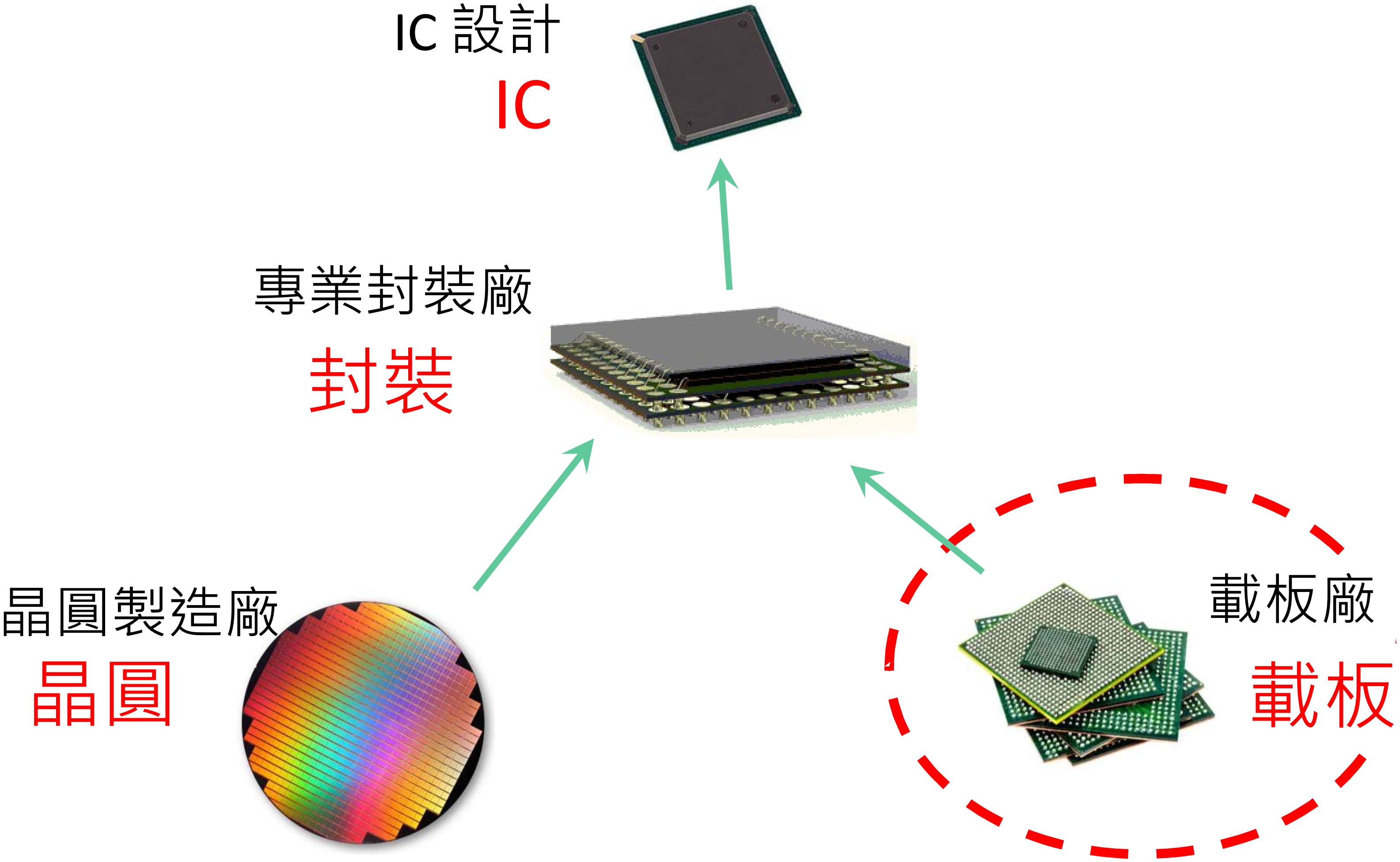


Advanced Packaging

CoWoS



IC 半導體上下游供應鏈關係



IC 設計

IC

專業封裝廠

封裝

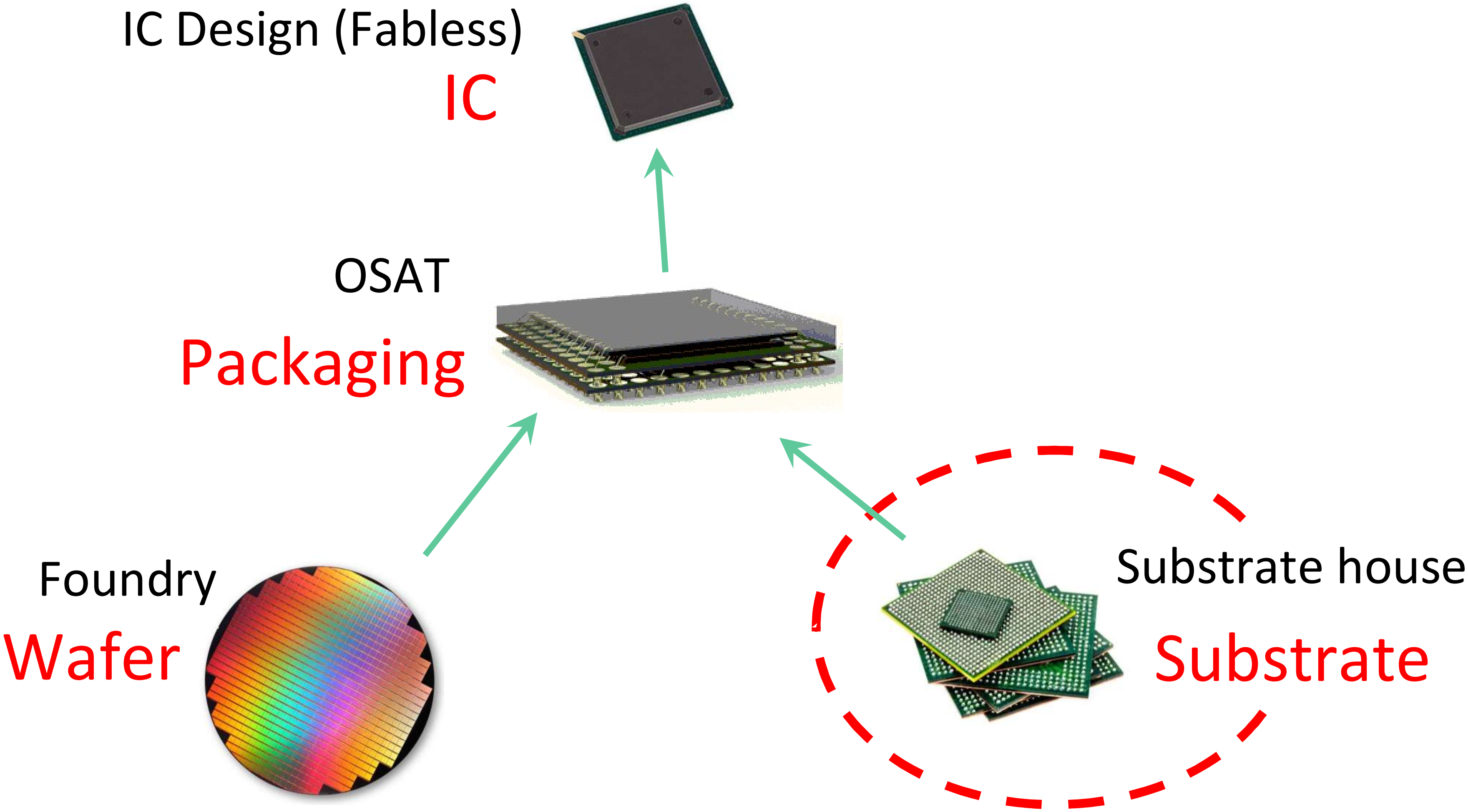
晶圓製造廠

晶圓

載板廠

載板

IC Manufacturing Supply Chain



IC Design (Fabless)

IC

OSAT

Packaging

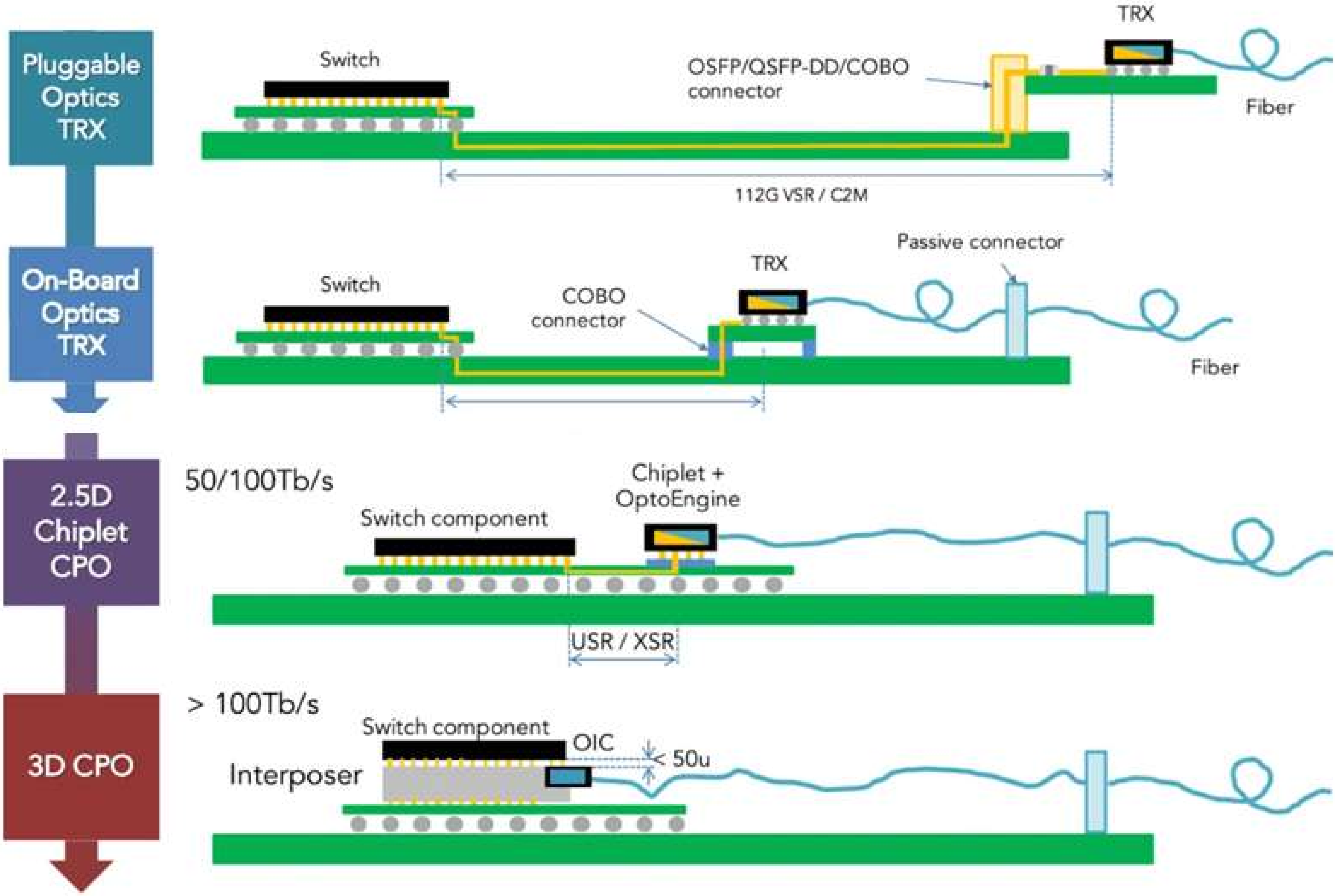
Foundry

Wafer

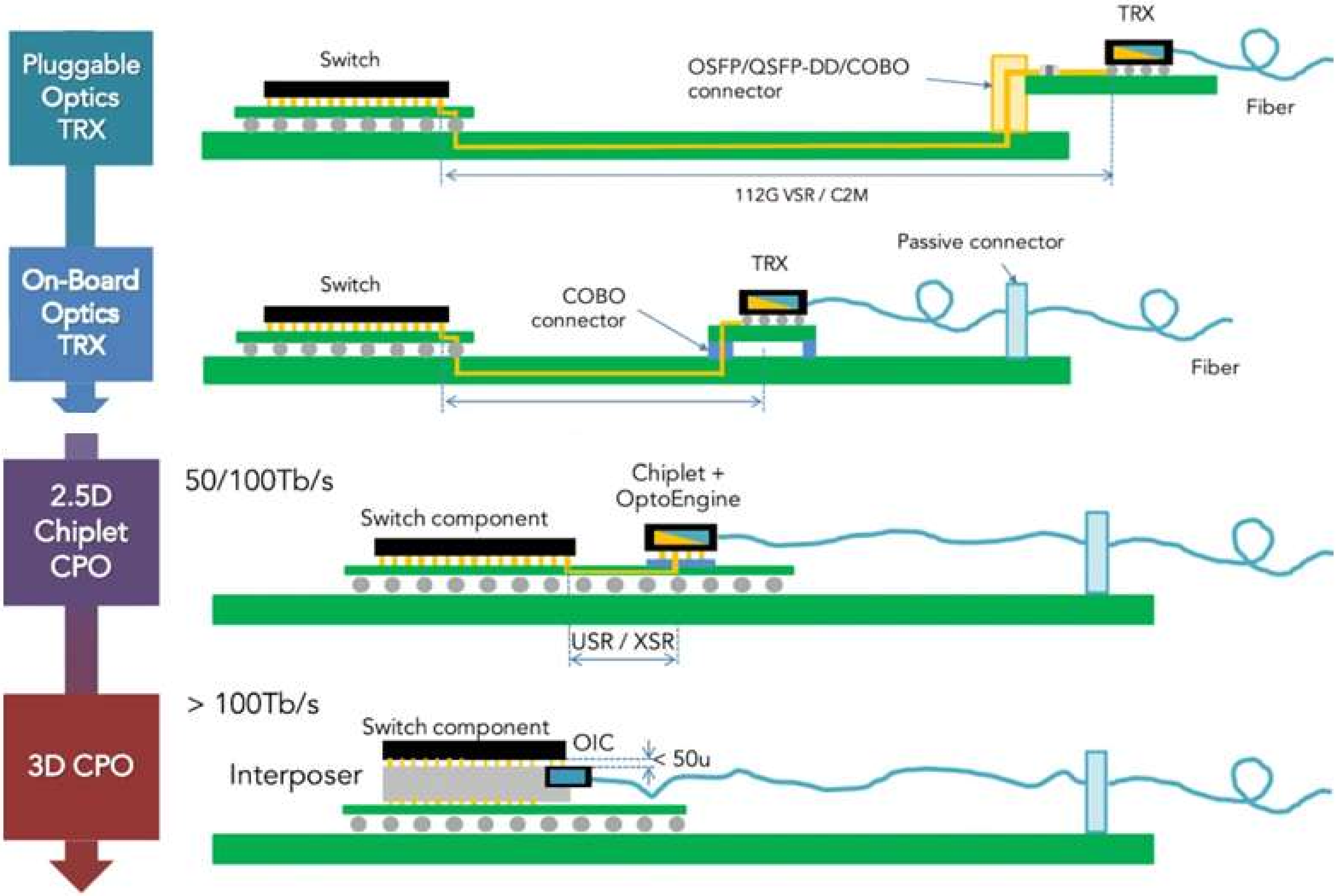
Substrate house

Substrate

光學共構封裝


Pluggable Optics TRX
Switch
OSFP/QSFP-DD/COBO connector
TRX
Fiber
112G VSR / C2M
On-Board Optics TRX
Switch
COBO connector
TRX
Passive connector
Fiber
2.5D Chiplet CPO
50/100Tb/s
Switch component
Chiplet + OptoEngine
USR / XSR
3D CPO
> 100Tb/s
Switch component
OIC
< 50u
Interposer

Co-Packaged Optics



About Kinsus

基本資料

• 公司成立	2000	
台股上市掛牌	2004	
• 資本額 :	新台幣 45.69 億元	
• 廠區 :	總部	- 新屋 / 台灣
	IC 載板	- 一廠 及 二廠
		- 五廠 及 六廠
	Kinsus USA	- Santa Clara / California
	統碩科技	- 蘇州 / 中國
	晶碩光學	- 桃園 / 台灣

Basic Information

- Established in September 2000
  IPO at TWSE in November 2004
- Capital : US$ 145 Million (NT$ 4.569 Billion)
- Campus :

Campus :	Headquarters	- Xin Wu / Taiwan
	IC substrates	- Plant 1 & 2
		- Plant 5 & 6
	Kinsus USA	- Santa Clara / California
	Kinsus China	- Suzhou / China
	PegaVision	- Taoyuan / Taiwan

位置

美國子公司

Kinsus Suzhou（統碩）

台灣一廠

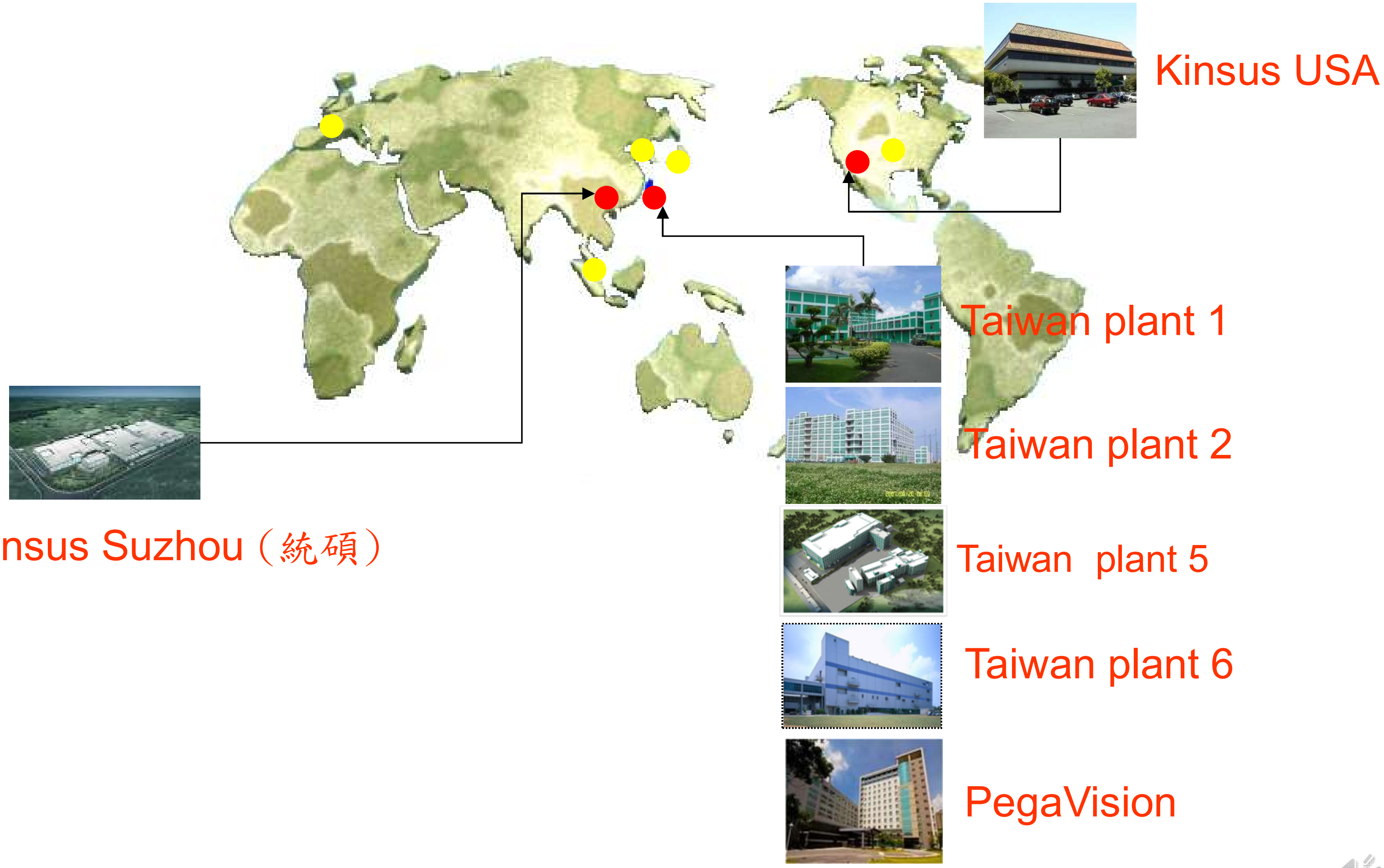
台灣二廠

台灣五廠

台灣六廠

晶碩光學

Locations



Kinsus USA

Taiwan plant 1

Taiwan plant 2

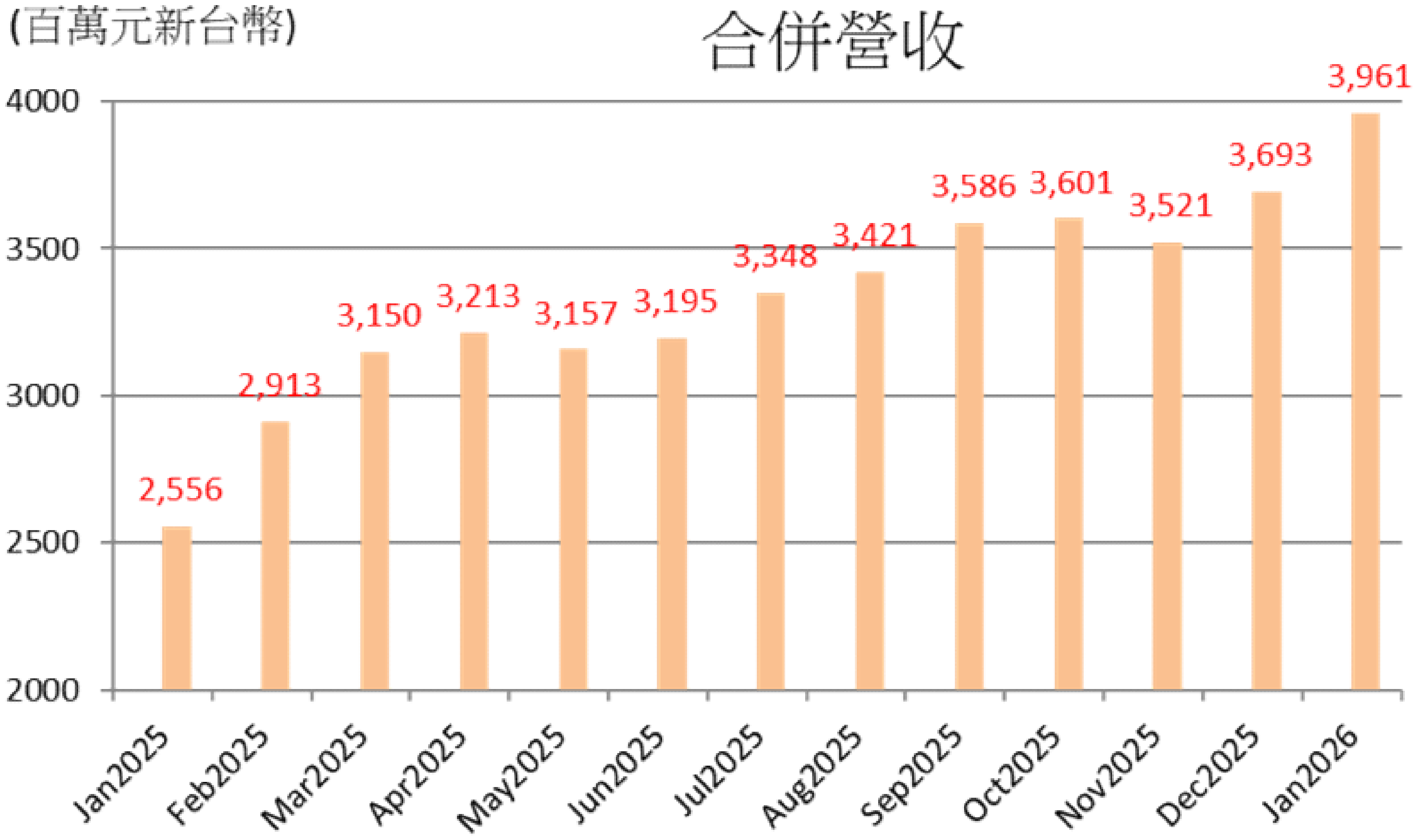
Taiwan plant 5

Taiwan plant 6

PegaVision

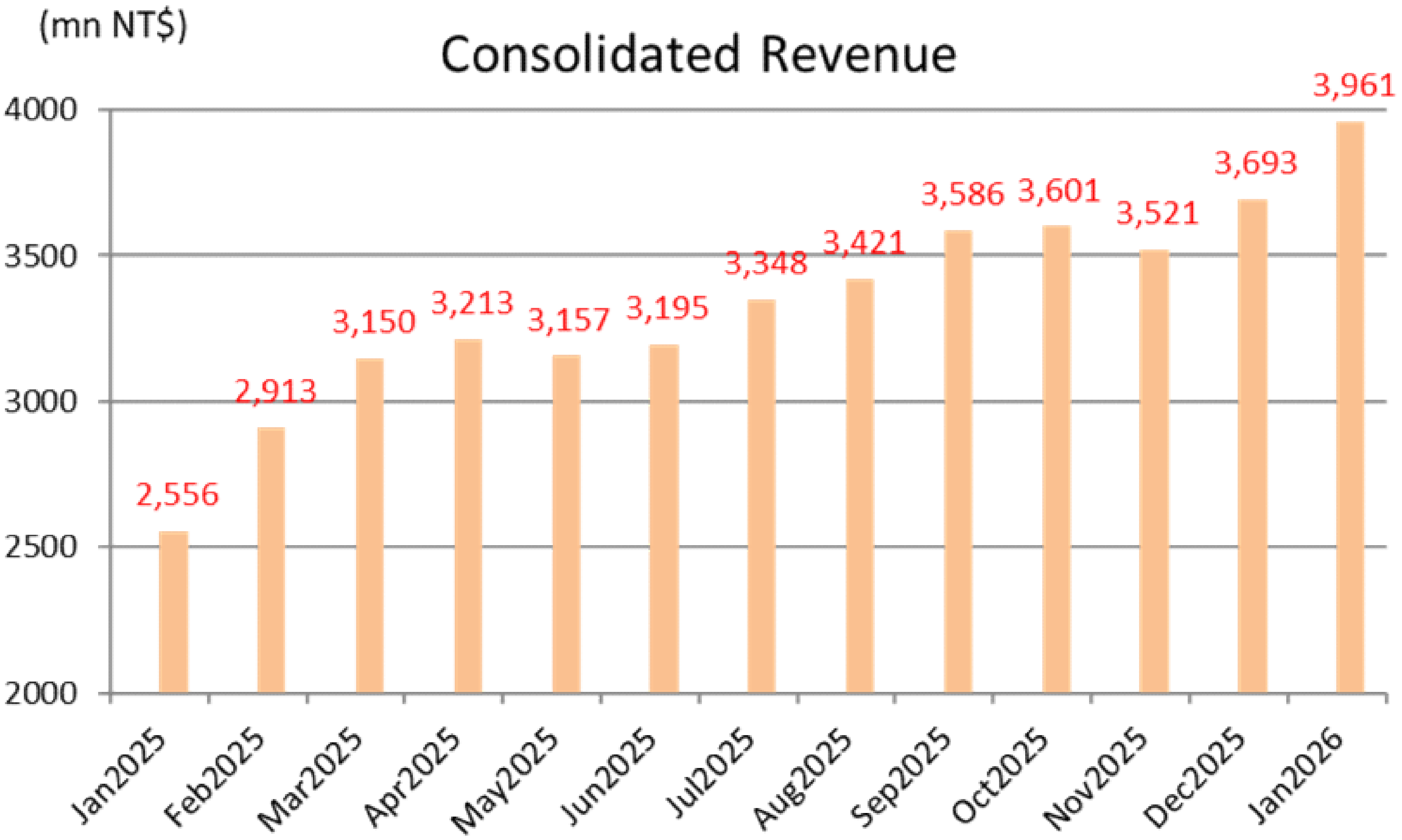
Kinsus Suzhou（統碩）

每月合併營業額

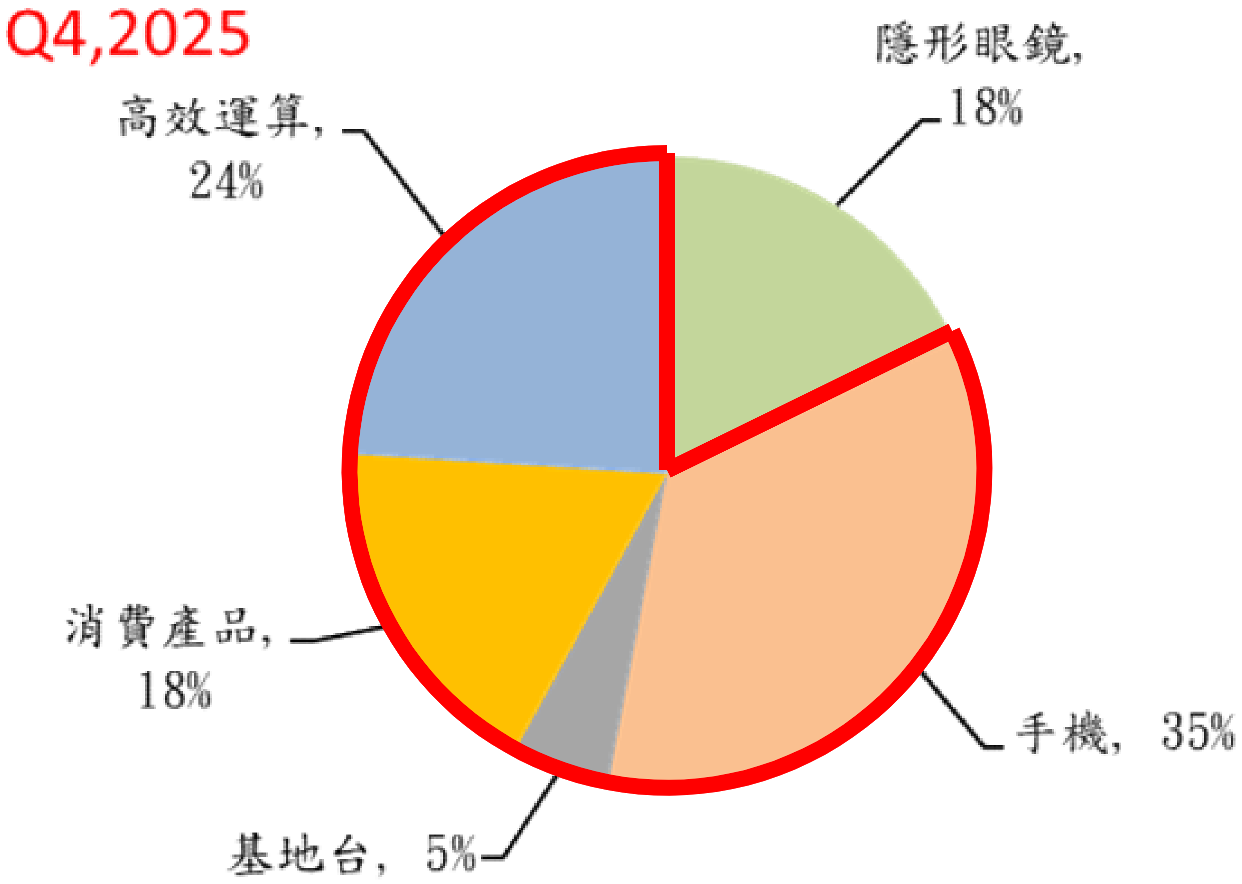


(百萬元新台幣)
合併營收
4000
3500
3000
2500
2000
2,556
2,913
3,150
3,213
3,157
3,195
3,348
3,421
3,586
3,601
3,521
3,693
3,961
Jan2025
Feb2025
Mar2025
Apr2025
May2025
Jun2025
Jul2025
Aug2025
Sep2025
Oct2025
Nov2025
Dec2025
Jan2026

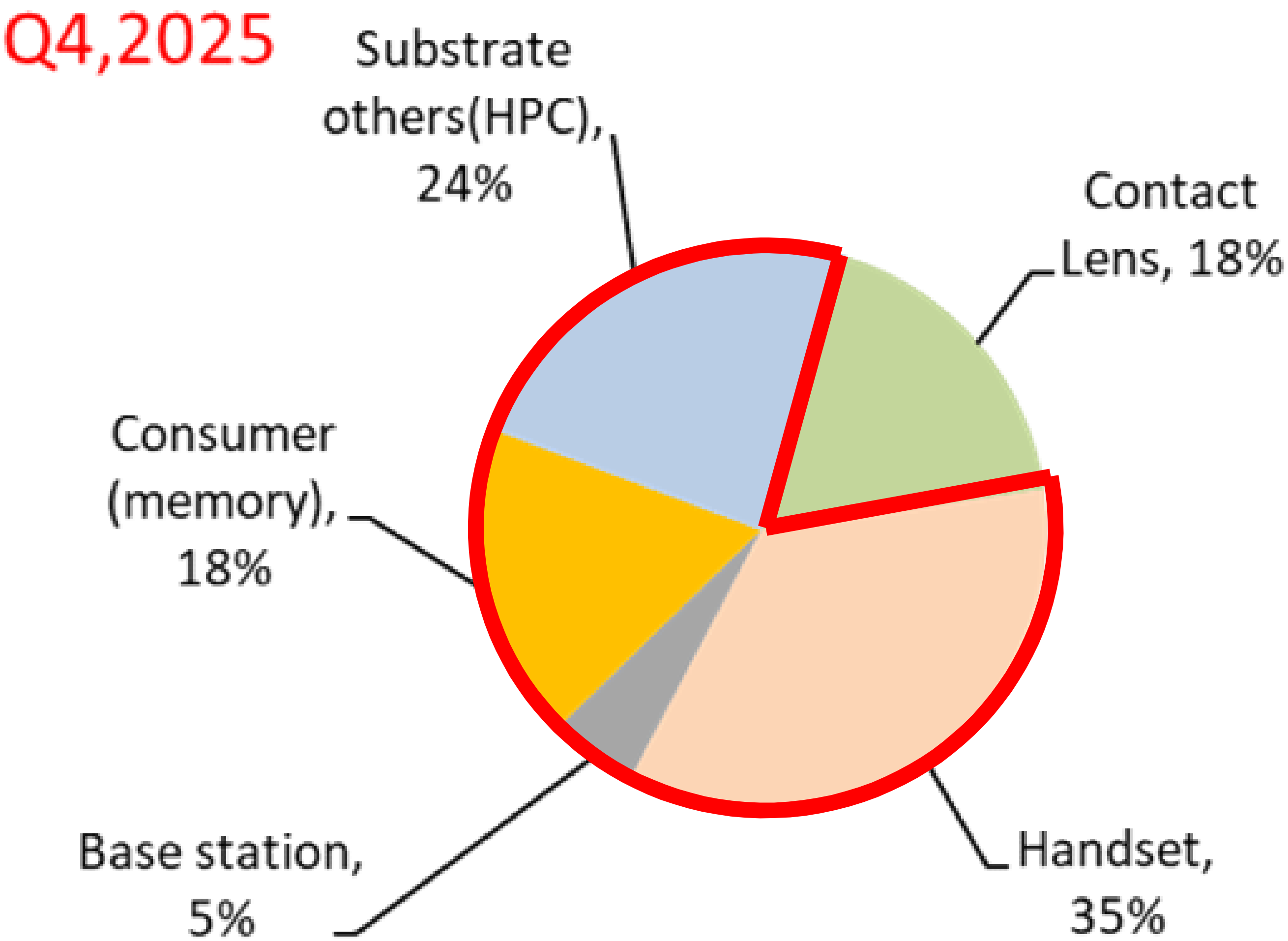
Monthly Consolidated Revenue



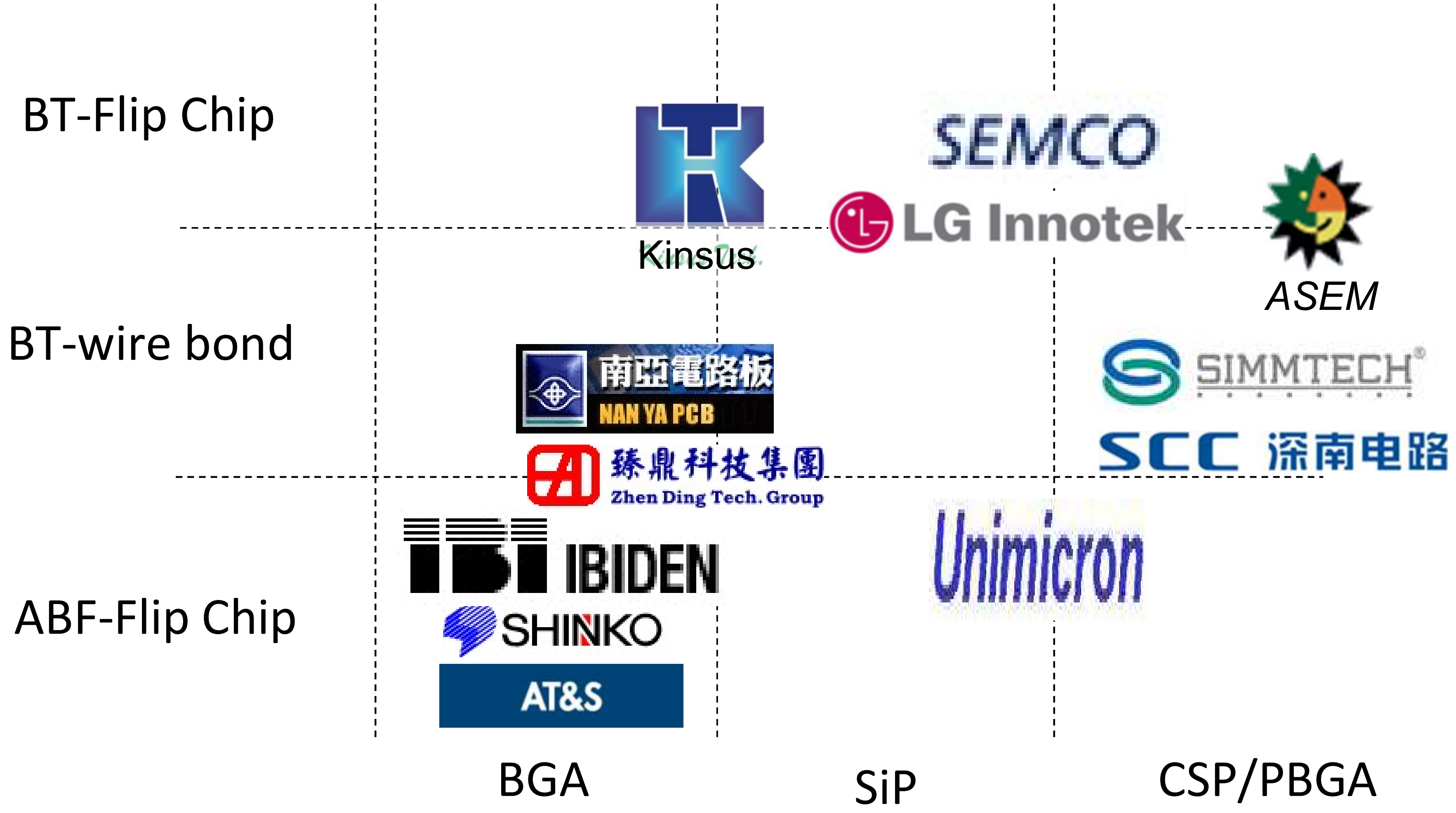
產品組合



Product mix


Q4,2025
Substrate others(HPC), 24%
Contact Lens, 18%
Consumer (memory), 18%
Base station, 5%
Handset, 35%

競爭格局



BT-Flip Chip

BT-wire bond

ABF-Flip Chip

BGA

SiP

CSP/PBGA

Kinsus

SEMCO

LG Innotek

ASEM

南亞電路板
NAN YA PCB

臻鼎科技集團
Zhen Ding Tech. Group

SIMMTECH

SCC 深南电路

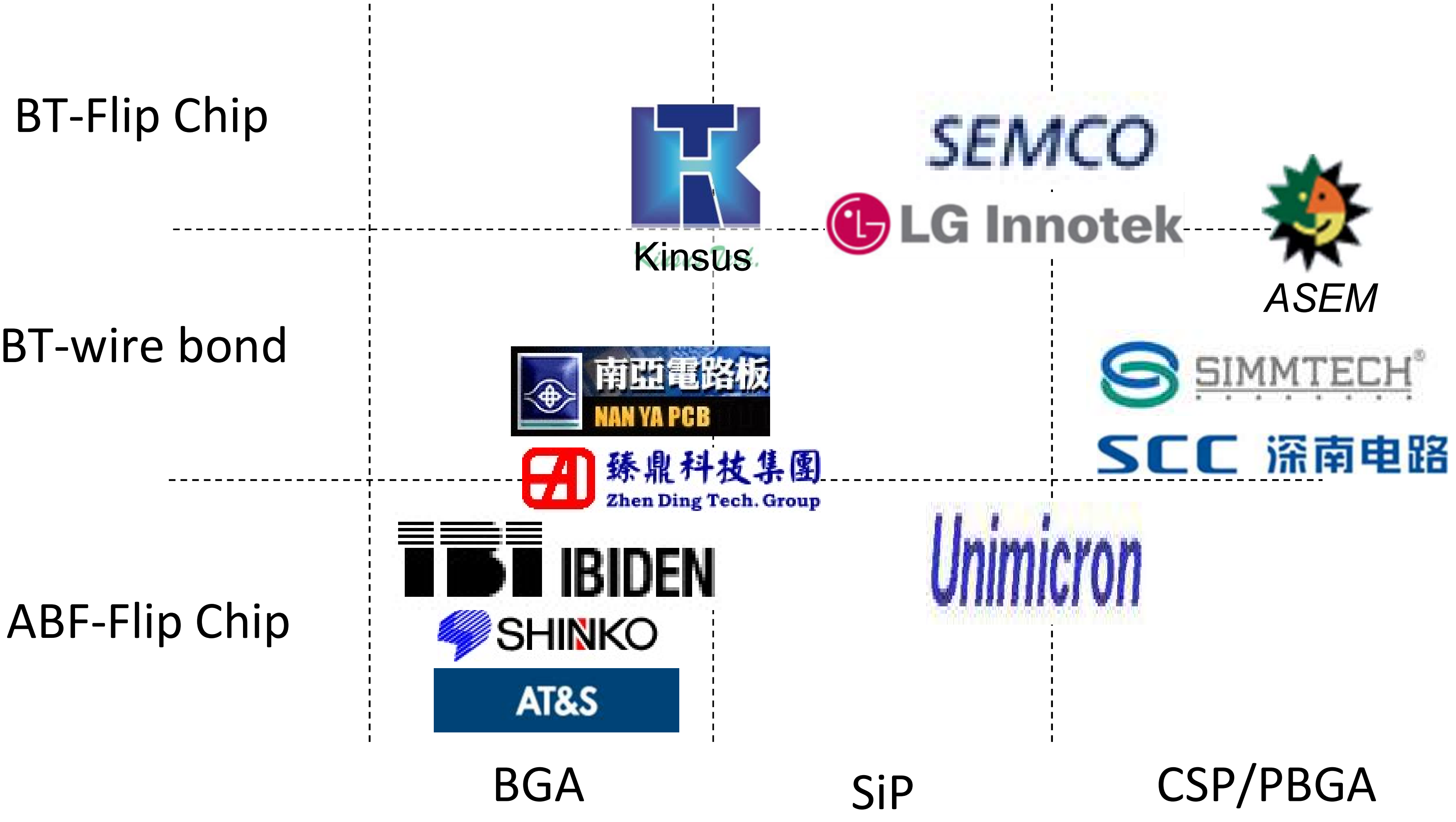
IBIDEN

SHINKO

AT&S

Unimicron

Competition Landscape



BT-Flip Chip

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SIMMTECH

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IBIDEN

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BGA

SiP

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Thank you